

**REMARKS**

Claims 2-14, 16-28, 31 and 32 are pending in the present application. Claims 2 and 17 have been amended.

**Drawings**

As noted in the Remarks section of the Amendment dated January 16, 2007, two (2) drawing Replacement Sheets were submitted along with the Amendment dated August 7, 2006, correcting Figs. 16 and 20. The drawing Replacement Sheets have been entered into the image file wrapper of the present application on the U.S. Patent Office website. Once again, the Examiner is respectfully requested to acknowledge receipt and acceptance of the drawing Replacement Sheets filed along with the Amendment dated August 7, 2006.

**Claim Rejections-35 U.S.C. 103**

Claims 2-7, 17-21, 31, and 32 have been rejected under 35 U.S.C. 103(a) as being unpatentable over the Mess et al. reference (U.S. Patent Application Publication No. 2002/0195697) in view of the Ohie reference (U.S. Patent No. 6,580,164). This rejection is respectfully traversed for the following reasons.

The semiconductor device of amended claim 2 includes in combination among other features "a second semiconductor chip having a surface on which a second electrode section is formed, and a back surface fixed to the surface of the first

semiconductor chip by an adhesive, wherein the adhesive is disposed on an entirety of the back surface of the second semiconductor chip." Applicant respectfully submits that the semiconductor device of claim 2 would not have been obvious in view of the prior art as relied upon by the Examiner for at least the following reasons.

The Examiner has primarily relied upon Fig. 12A and page 4 of the Mess et al. reference as meeting the features of claim 2. However, the Mess et al. reference does not specifically illustrate in Fig. 12A or describe on page 4 that an adhesive is disposed on an entirety of a back surface of semiconductor die 60B, as would be necessary to meet the features of claim 2. The Mess et al. reference generally describes in paragraph [0063] that semiconductor die 60B is attached to overlie a major portion of semiconductor die 60A. However, the Mess et al. reference fails to describe that an adhesive is disposed on an entirety of a back surface of semiconductor die 60B, including a portion of the back surface that protrudes from semiconductor die 60A. This should be particularly clear in view of FIG. 12 of the Mess et al. reference, which shows adhesive layer 78 only on the portion of semiconductor die 60B which overlaps with semiconductor die 60A. The Mess et al. structure thus does not reduce stress that acts on an edge portion of semiconductor die 60B as in the semiconductor device of claim 2. The Ohie reference as relied upon does not overcome these deficiencies of the Mess et al. reference. Applicant therefore respectfully submits that the semiconductor device of claim 2 would not have been obvious in view of the prior art as relied upon by the Examiner taken singularly or together, and that this rejection, insofar as it may pertain

to claims 2-7 and 31, is improper for at least these reasons.

The semiconductor device of amended claim 17 includes in combination among other features "a second semiconductor chip having a third surface fixed onto the second surface by an adhesive, a fourth surface opposite to the third surface, and a second electrode section formed on said fourth surface, wherein said fourth surface has a third side and a fourth side opposite to the third side, and wherein the adhesive is disposed on an entirety of the third surface."

As noted above, in the semiconductor device of claim 17, "the adhesive is disposed on an entirety of the third surface." Thus, Applicant respectfully submits that, for at least the reasons set forth above with regard to claim 2, the semiconductor device of claim 17 would not have been obvious in view of the prior art as relied upon by the Examiner taken singularly or together, and that this rejection, insofar as it may pertain to claims 17-21 and 32, is improper.

**Claims 31 and 32**

Applicant respectfully submits that claims 31 and 32 are generic. Applicant also respectfully submits that respective claims 31 and 32 would not have been obvious in view of the prior art as relied upon by the Examiner for at least the same reasons as set forth above, by virtue of dependency upon claims 2 and 17, respectively.

Conclusion

Applicant respectfully submits that claims 2-7, 17-21, 31, and 32 should be allowable for at least the above reasons. Applicant also respectfully requests the Examiner to rejoin claims 8-14, and claims 16 and 22-28, which should be allowable at least by virtue of dependency upon generic claims 2 and 7, respectively.

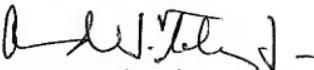
Accordingly, the Examiner is respectfully requested to reconsider and withdraw the corresponding rejection, and to pass all the claims of the present application to issue, for at least the above reasons.

In the event that there are any outstanding matters remaining in the present application, please contact Andrew J. Telesz, Jr. (Reg. No. 33,581) at (571) 283-0720 in the Washington, D.C. area, to discuss these matters.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment for any additional fees that may be required, or credit any overpayment, to Deposit Account No. 50-0238.

Respectfully submitted,

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